

JAPANESE PATENT OFFICE

PATENT JOURNAL

KOKAI PATENT APPLICATION NO. SHO 64[1989]-50551

Int. Cl. ⁴ :	H 01 L 25/14 23/50
Sequence Nos. for Office Use:	Z-7638-5F W-7735-5F
Application No.:	Sho 62[1987]-208728
Application Date:	August 21, 1987
Publication Date:	February 27, 1989
No. of Inventions:	1 (Total of 3 pages)
Examination Request:	Not requested

IC PACKAGE STRUCTURE

Inventor:	Nobuyuki Yanagi, NEC, 5-33-1 Shiba, Minato-ku, Tokyo
Applicant:	NEC, 5-33-1 Shiba, Minato-ku, Tokyo
Agent:	Susumu Uchihara, patent attorney

[There are no amendments to this patent.]

Claims

1. IC package structure characterized in that it has a first IC package, a first connecting terminal provided on a first surface of this first IC package and connected to a first electronic component, as well as a second connecting terminal provided on a second surface opposite from the first surface of the aforementioned first IC package and connected to a second electronic component.

2. The IC package structure described in Claim 1, characterized in that the aforementioned first electronic component is a second IC package and the aforementioned second electronic component is a printed circuit board.

3. The IC package structure described in Claim 1, characterized in that the aforementioned first and second electronic components are both printed circuit boards.

* * *